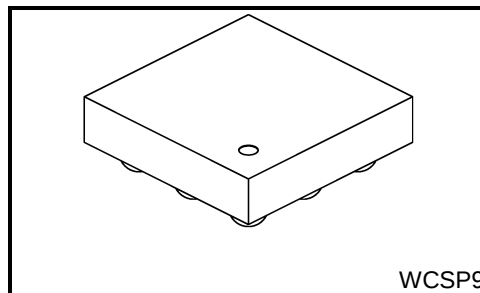


TCK301G, TCK302G, TCK303G

28 V, Single input – Single Output Load Switch IC with Over Voltage Protection

The TCK30 series are 28 V high input voltage Single Inputs—Single Output load switch ICs. It has Over Voltage Protection function featuring low switch ON resistance, high output current and wide input voltage operation. Switch ON resistance is only 73 mΩ at 4.5 V, - 1.0 A load conditions. And these feature a slew rate control driver, thermal shutdown and FLAG function. Also it can block reverse current if switch turned off. Output current is available up to 3 A. Thus this is suitable for power management such as Battery Charge application.

This device is available in 0.5mm pitch ultra small package WCSP9 (1.5 mm x 1.5 mm, t: 0.5 mm (Typ.)). Thus this device is ideal for portable applications that require high-density board assembly such as cellular phone.

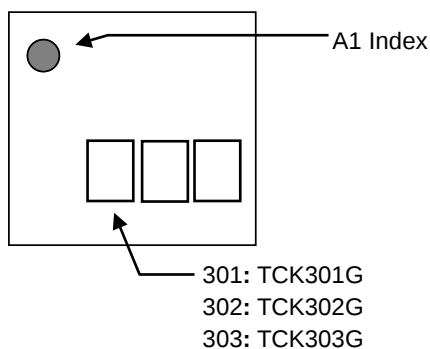


Weight: 3.5 mg (Typ.)

Feature

- High input voltage: $V_{IN} (Max) = 28 V$
- High output current: $I_{OUT} (DC) = 3.0 A$
- Low ON resistance : $R_{ON} = 73 m\Omega (Typ.)$ at $V_{IN} = 4.5 V$, $I_{OUT} = - 1.0 A$
- Over Voltage Lockout : 6.6 V, 10.5 V, and 15.5 V (Typ.)
- Under Voltage Lockout: 2.9 V (Typ.)
- FLAG indicates
- Internal 15 ms startup hold
- Reverse current blocking (SW OFF state)
- Inrush current reducing circuit
- Thermal Shutdown function
- Small package: 0.5 mm pitch WCSP9 (1.5 mm x 1.5 mm, t: 0.5 mm (Typ.)) , $P_D = 1.65 W$

Top marking



Start of commercial production
2015-05

Absolute Maximum Ratings (Ta = 25°C)

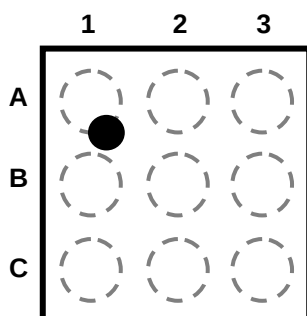
Characteristics	Symbol	Rating		Unit
Input voltage	V _{IN}	-0.3 to 30		V
Control voltage	V _{CT} , V _{CE}	-0.3 to 6		V
Output voltage	V _{OUT}	-0.3 to 18		V
Flag voltage	V _{FLAG}	-0.3 to 6		V
Output current	I _{OUT}	DC	3.0	A
		Pulse	4.0 (Note 1)	
Power dissipation	P _D	1.65 (Note 2)		W
Operating temperature range	T _{opr}	-40 to 85		°C
Junction temperature	T _j	150		°C
Storage temperature	T _{stg}	-55 to 150		°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note1: 1 ms pulse, 1% duty cycle

Note2: Rating at mounting on a board: FR4 board. (40 mm × 40 mm × 1.6 mm, Cu 4 layer)

Pin Assignment (Top view/Bottom bump)



	1	2	3
A	FLAG	V _{CT}	$\overline{\text{CE}}$
B	V _{IN}	GND	V _{OUT}
C	V _{IN}	GND	V _{OUT}

Product list

Part number	Over voltage lockout	$\overline{\text{CE}}$ function	VCT function	VCT resistance
TCK301G	6.6 V (Typ.)	Active Low	Active High	Pull up
TCK302G	10.5 V (Typ.)	Active Low	Active High	Pull up
TCK303G	15.5 V (Typ.)	Active Low	Active High	Pull up

Please ask your local retailer about the devices with other OVLO, logic function and pull up resistance.

The diagram illustrates the internal architecture of the L64290 microcontroller. Key components include:

- Input Pins:** V_{IN} (two pins), $\overline{CE}$ (Chip Enable), and V_{CT} (Control Temperature).
- Internal Blocks:**
 - OVLO/UVLO:** Overvoltage/Undervoltage Lockout.
 - Charge Pump:** Provides a boosted voltage to the **Inrush Current Reducing** block.
 - Inrush Current Reducing:** Manages the initial surge current.
 - Control Logic:** The central processing unit that coordinates the device's operation.
 - Thermal Shutdown:** Protects the device from overheating.
 - Reverse Current Blocking:** Prevents current from flowing back into the output.
- Output and Status Pins:**
 - V_{OUT} :** The main output voltage, connected to a MOSFET (Q_1).
 - FLAG:** A status pin connected to another MOSFET (Q_2), configured as an open drain.
- Internal Circuitry:** The diagram shows various internal transistors, resistors, and logic gates that facilitate the control and protection functions.

PIN	Name	Description
A1	FLAG	Open drain acknowledge signal output. When input voltage is in regular range ($V_{UVL} < V_{IN} < V_{OVL}$), Q_2 turn ON. FLAG output turn to be high impedance in irregular input voltage range, CE High state and thermal shutdown operation.
A2	V_{CT}	Switch Control function. It is internally connected to VOP (Pull up).
A3	CE	Chip Enable function. It is internally connected to GND(Pull down).
B1, C1	V_{IN}	Input. It has Over Voltage Lock Out (OVLO) and Under Voltage Lock Out function (UVLO).
B2, C2	GND	Ground
B3, C3	V_{OUT}	Output

		CE “Low”	CE “ High”
V _{CT} “HIGH”	Q ₁ (Main Switch)	ON	OFF
	Q ₂ (FLAG out)	ON (When V _{UVL} < V _{IN} < V _{OVL}), OFF (When V _{UVL} > V _{IN} , or V _{IN} > V _{OVL}), OFF (Thermal shut down = active)	OFF
	Reverse current block	Disable	Active
V _{CT} “LOW”	Q ₁ (Main Switch)	OFF	OFF
	Q ₂ (FLAG out)	ON (When V _{UVL} < V _{IN} < V _{OVL}), OFF (When V _{UVL} > V _{IN} , or V _{IN} > V _{OVL}), OFF (Thermal shut down = active)	OFF
	Reverse current block	Active	Active

DC Characteristics (Ta = -40 to 85°C)

Characteristics	Symbol	Test Condition	Ta = 25°C			Ta = -40 to 85°C		Unit
			Min	Typ.	Max	Min	Max	
Input voltage	V _{IN}	—	2.3	—	28	2.3	28	V
$\overline{\text{CE}}$, V _{CT} High-level input voltage	V _{IH}	V _{IN} = 2.3 to 28 V	1.6	—	—	1.6	—	V
$\overline{\text{CE}}$, V _{CT} Low-level input voltage	V _{IL}	V _{IN} = 2.3 to 28 V	—	—	0.3	—	0.3	V
Over voltage lock out (OVLO) rising threshold	V _{OVLO_RI}	TCK301G	—	6.6	—	5.9	7.3	V
		TCK302G	—	10.5	—	9.1	11.9	
		TCK303G	—	15.5	—	13.9	17.1	
Over voltage lock out (OVLO) falling threshold	V _{OVLO_FA}	TCK301G	—	V _{OVLO_RI} - 0.35	—	—	—	V
		TCK302G, TCK303G	—	V _{OVLO_RI} - 0.5	—	—	—	
Under voltage lock out (UVLO) rising threshold	V _{UVLO_RI}	—	—	2.9	—	2.3	3.5	V
Under voltage lock out (UVLO) falling threshold	V _{UVLO_FA}	—	—	V _{UVLO_RI} - 0.3	—	—	—	V
Quiescent current (ON state)	I _{Q(ON)}	$\overline{\text{CE}}$ = Open, V _{CT} = Open I _{OUT} = 0 mA, V _{IN} = 5.0 V	—	130	—	—	190	μA
Quiescent current (OFF state)	I _{Q(OFF1)}	$\overline{\text{CE}}$ = 0 V, V _{CT} = 0 V, V _{IN} = 5.0 V, V _{OUT} = 0 V	—	75	—	—	115	μA
Input Shutdown Current	I _{Q(OFF2)}	$\overline{\text{CE}}$ = 3.0 V, V _{CT} = Open, V _{IN} = 5.0 V, V _{OUT} = 0 V	—	1.3	—	—	10	μA
Switch OFF state current	I _{OFF}	$\overline{\text{CE}}$ = 3.0 V, V _{CT} = Open, V _{IN} = Open, V _{OUT} = 5 V	—	0.1	—	—	1	μA
Reverse blocking current	I _{RB}	V _{OUT} = 5.0 V, V _{IN} = 0 V, V _{CT} = 0 V	—	0.1	—	—	10	μA
On resistance	R _{ON}	I _{OUT} = -1.0 A, V _{IN} = 4.5 V	—	73	—	—	140	mΩ
FLAG Leak current	I _{LEAK}	V _{IO} = 5.0 V	—	—	2	—	2	μA
FLAG Output low voltage	V _{OL}	I _{SINK} = 1 mA, V _{IO} = 5.0 V	—	—	0.4	—	0.4	V
$\overline{\text{CE}}$ built-in resistance	R _{CE}	—	—	530	—	—	—	kΩ
V _{CT} built-in resistance	R _{VCT}	—	—	530	—	—	—	

AC Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition (Figure 1, 2)	Min	Typ.	Max	Unit
Hold time	t _{HD}	V _{UVLO} < V _{IN} (5V) < V _{OVLO} , R _L = 50 Ω Initial start up V _{OUT} off state to charge-pump on state	—	15	—	ms
V _{OUT} OVP off time	t _{OVP}	V _{IN} > V _{OVLO_RI} , V _{IN} rising = 2V/μs, R _L = 50 Ω, V _{OUT} to 80% of V _{OVLO_RI}	—	3	—	μs
V _{OUT} off time	t _{OFF}	V _{UVLO} < V _{IN} (5V) < V _{OVLO} , R _L = 50 Ω, V _{OUT} to 80% of V _{IN}	—	2	—	μs
V _{OUT} rise time	t _r	V _{IN} = 5.0V, R _L = 50 Ω, C _L = 1.0 μF	—	2	—	ms
V _{OUT} fall time	t _f	V _{IN} = 5.0V, R _L = 50 Ω, C _L = 1.0 μF	—	0.12	—	ms
V _{CT} delay time (Enable to Disable)	t _{CT1}	V _{IN} = 5.0V, R _L = 50 Ω	—	0.5	—	μs
V _{CT} delay time (Disable to Enable)	t _{CT2}	V _{IN} = 5.0V, R _L = 50 Ω	—	3.2	—	ms

Timing chart

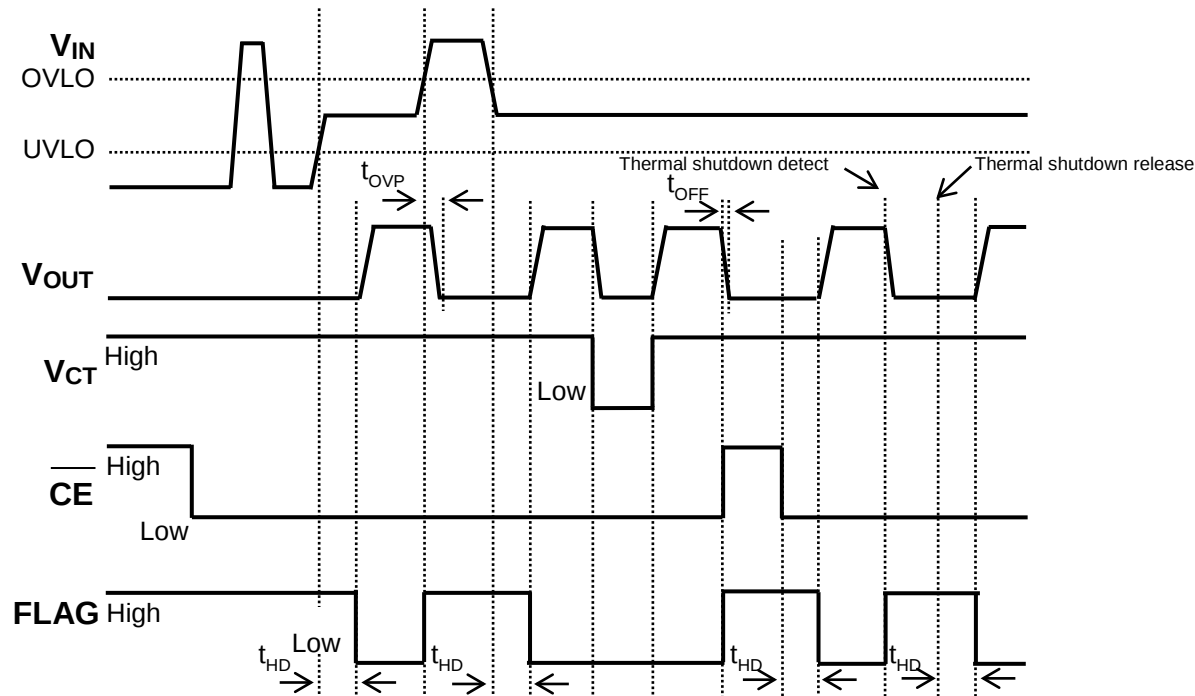


Fig.1 t_{HD} , t_{OVP} , t_{OFF}

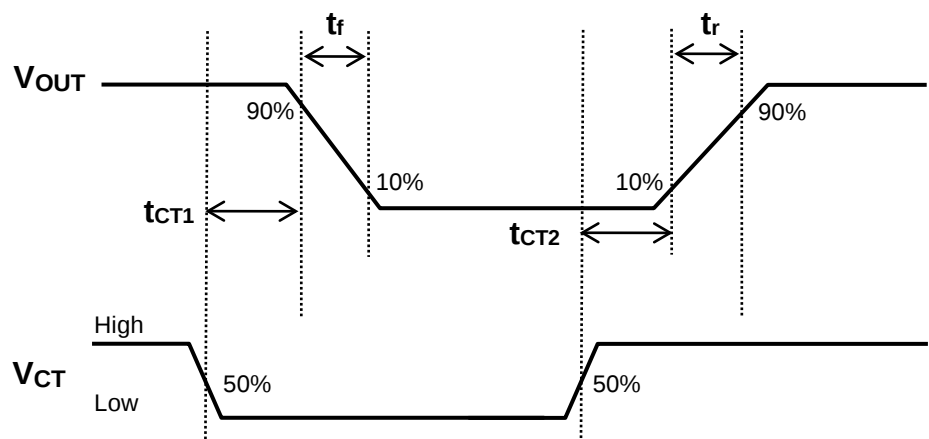
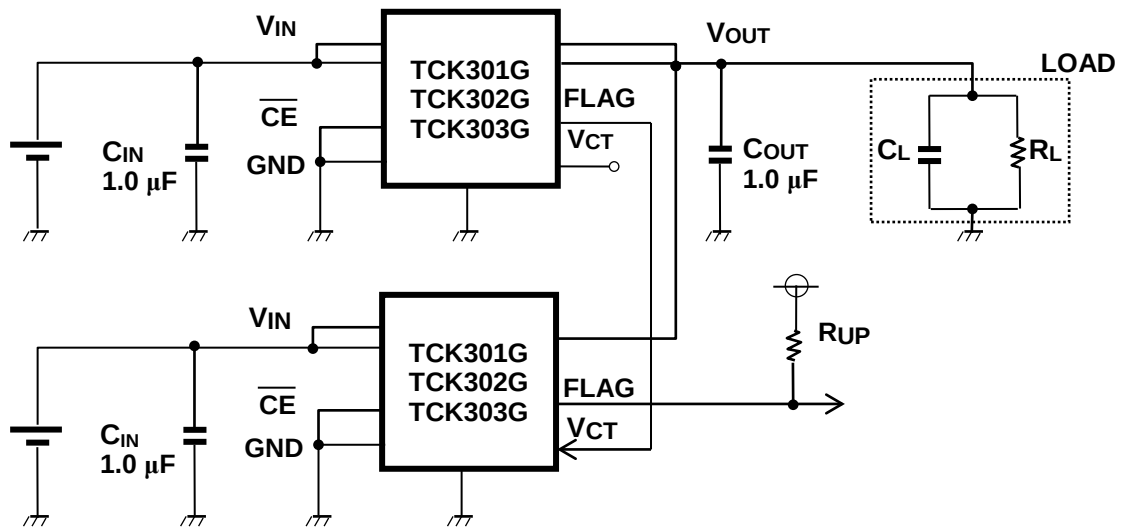


Fig.2 t_r , t_r , t_{CT}

Application Note

1. Application circuit example (top view)



1) Input and Output capacitor

An input capacitor (C_{IN}) and an output capacitor (C_{OUT}) are necessary for the stable operation of TCK301G, TCK302G and TCK303G. And it is effective to reduce voltage overshoot or undershoot due to sharp changes in output current and also for improved stability of the power supply. When used, place C_{IN} and C_{OUT} more than $1.0\mu F$ as close to V_{IN} pin to improve stability of the power supply.

2) Control pin

Control pins for TCK301G, TCK302G and TCK303G is operated by the control voltage and Schmitt trigger. V_{CT} pin has a tolerant function such that it can be used even if the control voltage is higher than the input voltage.

2. Reverse current blocking

Reverse current blocking (SW OFF state) function is designed in these products. This function is active at output n-ch MOSEFT turned off.

However these does not assure for the suppression of uprising device operation. In use of these products, please read through and understand dissipation idea for absolute maximum ratings from the above mention or our 'Semiconductor Reliability Handbook'. Then use these products under absolute maximum ratings in any condition. Furthermore, Toshiba recommend inserting failsafe system into the design.

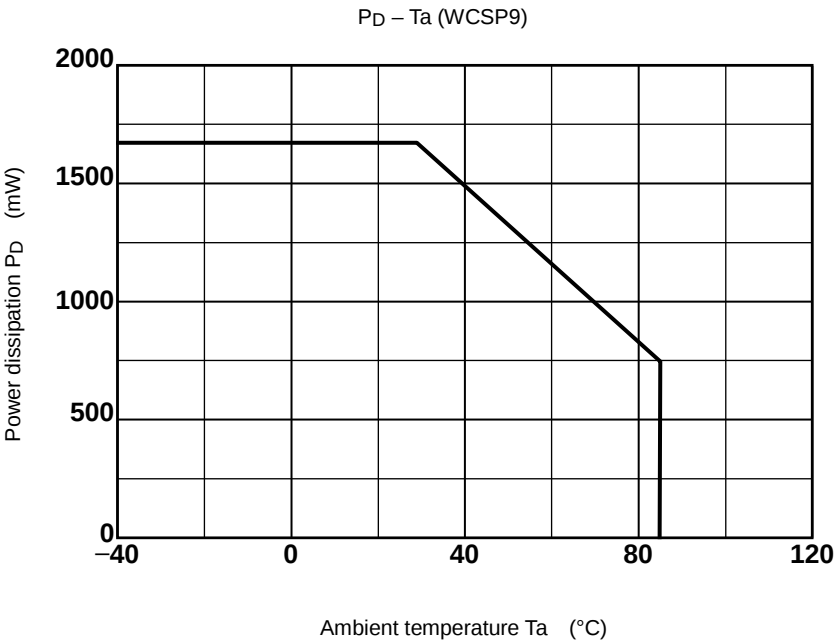
3. Thermal shut down function

Thermal shutdown function is designed in these products, but these does not assure for the suppression of uprising device operation. In use of these products, please read through and understand dissipation idea for absolute maximum ratings from the above mention or our 'Semiconductor Reliability Handbook'. Then use these products under absolute maximum ratings in any condition. Furthermore, Toshiba recommend inserting failsafe system into the design.

4. Power Dissipation

Board-mounted power dissipation ratings for TCK301G, TCK302G and TCK303G are available in the Absolute Maximum Ratings table.
Power dissipation is measured on the board condition shown below.

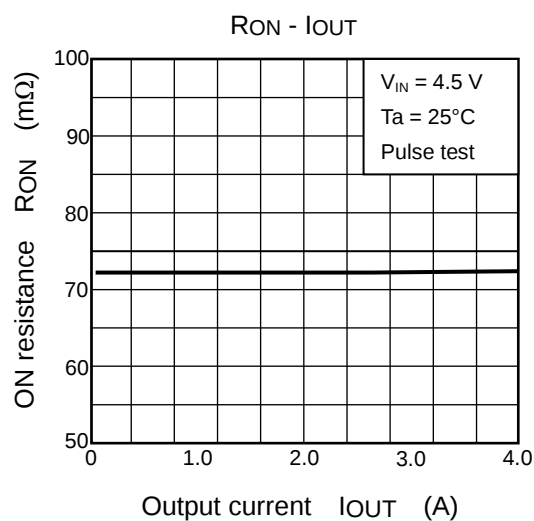
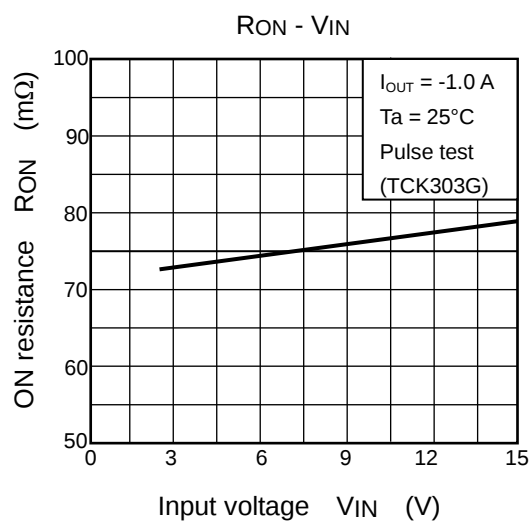
[The Board Condition]
Board material: Glass epoxy (FR4)
Board dimension: 40 mm x 40 mm (Cu 4 layer)



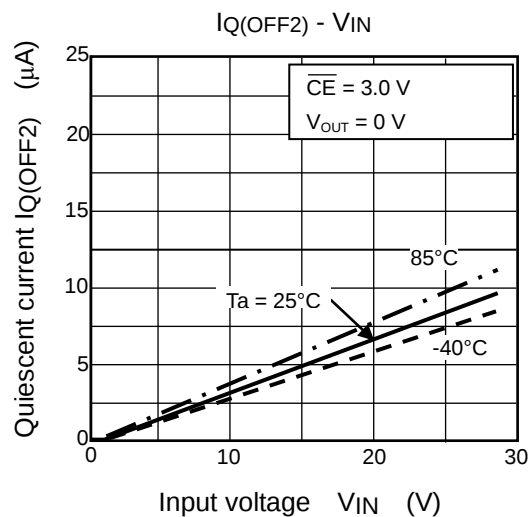
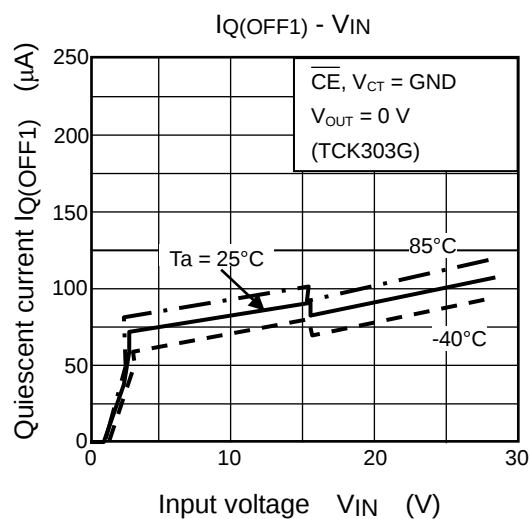
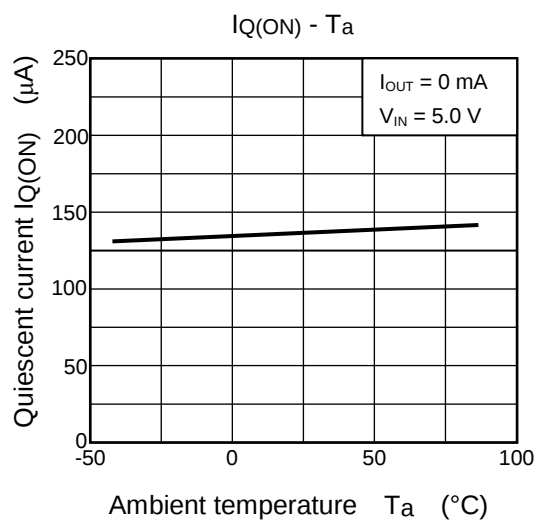
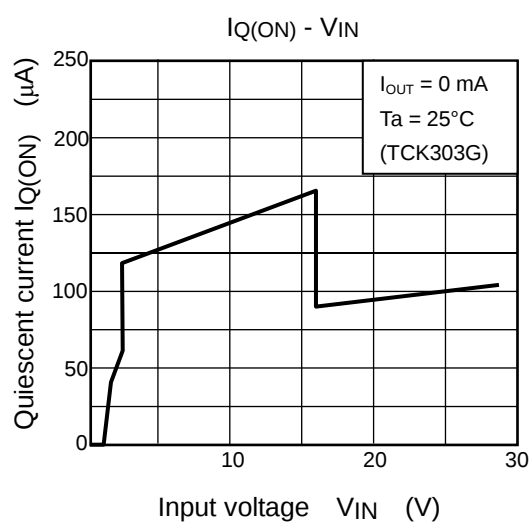
Please allow sufficient margin when designing a board pattern to fit the expected power dissipation. Also take into consideration the ambient temperature, input voltage, output current etc. and applying the appropriate derating for allowable power dissipation during operation.

Representative Typical Characteristics

1) ON resistance



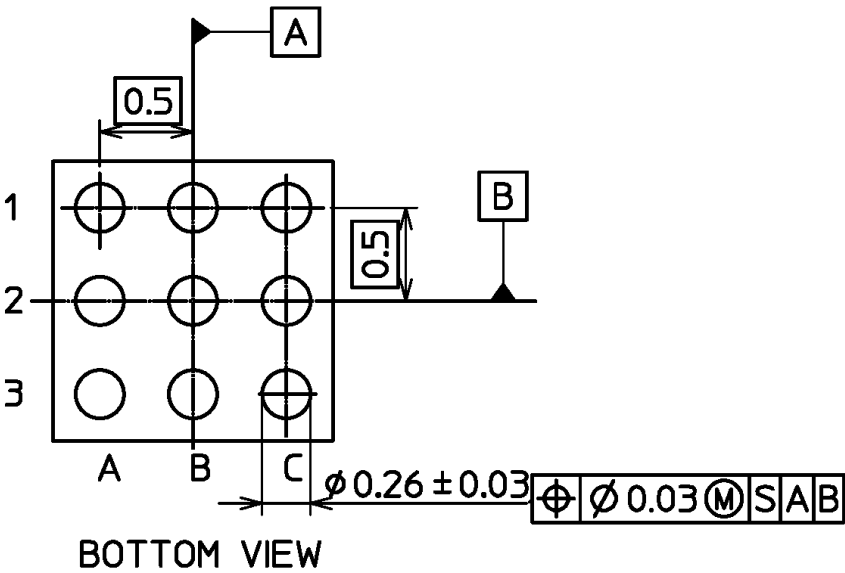
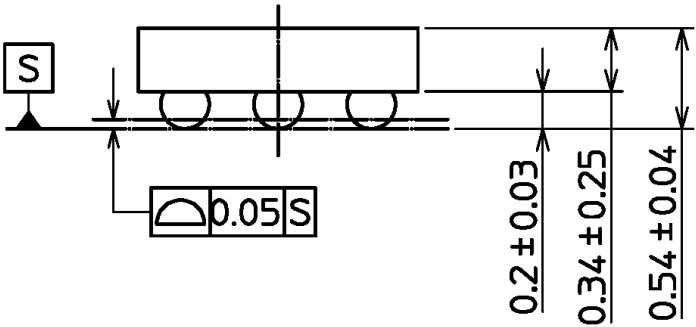
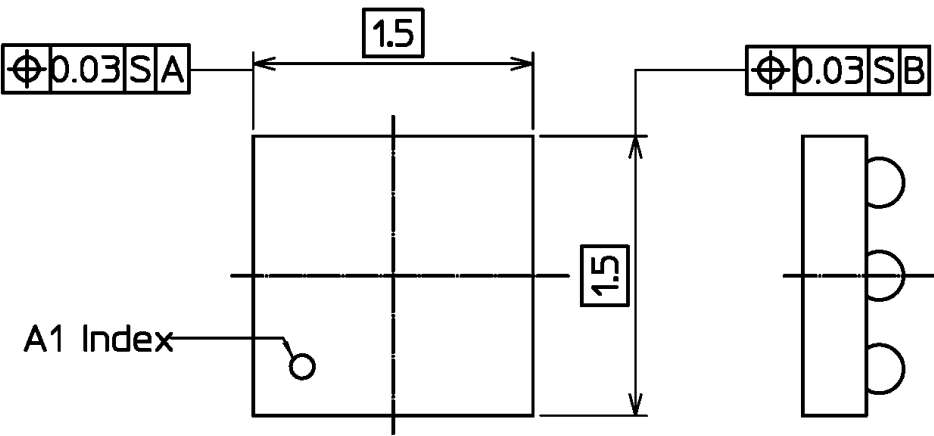
2) Quiescent current



Package Dimensions

WCSP9

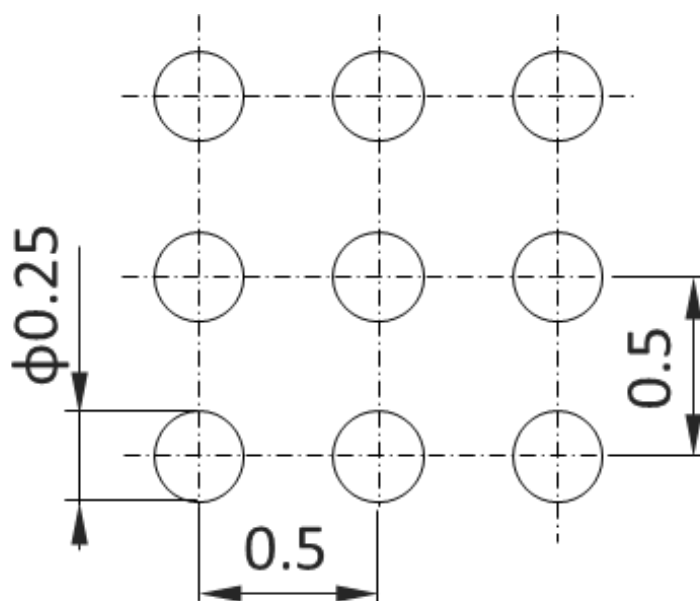
Unit: mm



Weight: 3.5 mg (Typ.)

Land pattern dimensions (for reference only)

Unit: mm



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